AXIS 1064

Technical Data Sheet

AXIS 1064 is a low viscosity, UV-curable adhesive that will fluoresce under a black light to facilitate inspection of bonded assemblies. AXIS 1064 has a secondary heat cure that enables curing in shadowed areas. AXIS 1064 was designed for bonding stainless steel cannula into hubs, syringes, and lancets for needle assembly. Resin Designs medical device adhesives contain no nonreactive solvents and have been tested for biocompatibility per ISO 10993-5, cytotoxicity.

APPLICATIONS	FEATURES	SUBSTRATES
• Needle bonding	• UV curable	• Plastics
• Transducer assembly	• Fluorescing	• Metals
	• Secondary heat cure	• Ceramics
	• Biocompatibility per ISO 10993-5	

Typical Properties of Uncured Material*

Chemical Class	Acrylated urethane
Color	Clear
Viscosity @25°C, Spn1 @20RPM, cps	50 to 225
Specific Gravity	1.02
Cleanup Solvent	Isopropyl alcohol

UV Light Cure Guidelines*

Recommended Curing Spectrum	UVA
Minimum dosage required, J/cm^2	3

Heat is also an important component with UV cure, and different systems produce different heat outputs. Cure testing was done in an open system and results will vary with application. Consequently, Resin Designs recommends that curing is discussed with our Technical staff to ensure the exact customer process being used will meet the coating cure requirements.

Secondary Cure Guidelines*

Cure Mechanism	Heat
Cure Time @ 125°C, minutes	10

AXIS 1064 was designed to be cured using a microwave UV oven. Arc and LED systems may cure AXIS 1064; however, care must be taken during the equipment selection process to ensure minimum dosage and irradiance values obtained will properly cure the coating. Because of the variations possible in curing equipment type and configuration, it is strongly recommended that you contact Resin Designs Technical Support to discuss your equipment and process in detail.

Typical Properties of Cured Material*

Durometer, Shore D	75
Elongation, %	5
Tensile Strength, MPa, [psi]	29.6, [4300]
Compressive Modulus @ -55°C, MPa	417
Compressive Modulus @ 25°C, MPa	195
Compressive Modulus @ 145°C, MPa	0.5
Glass Transition Temperature (Tg), °C	78
Lap Shear Strength, PCB / PCB, psi	190
Temperature at 1% wt. loss, °C	163
Temperature at 5% wt. loss, °C	288
Processing Temperature Range, °C	-55 to 145

***All properties given are typical values and are not intended for use in preparing specifications.**

Storage

Keep stored between 8°C and 28°C in tightly closed, light-blocking containers away from direct sunlight. Keep from freezing. Please refer to product labeling for shelf-life information. Consult SDS for safe handling recommendations.

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